



Title of Change:	NCP3170 Back Metal Process Improvement at UMC to resolve Peeling Issue.		
Proposed first ship date:	5 September 2015		
Contact information:	Contact your local ON Semiconductor Sales Office or Rob Prestoza <rob.prestoza@onsemi.com>		
Samples:	Contact your local ON Semiconductor Sales Office		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Donna Scheuch <donna.scheuch@onsemi.com>.		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.		
Change Part Identification:	There is no physical change with the top marking of the device.		
Change category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Material Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____		
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) : <input checked="" type="checkbox"/> External Foundry/Subcon site(s):	Site 1 UNITED MICROELECTRONICS CORP USA	Site 2
Description and Purpose:			
ON Semiconductor is pleased to announce the implementation of Process Improvements at United Microelectronics Corp (UMC), a Wafer Fabrication facility located in Taiwan, to resolve the Peeling Issue on the High Side FET die for NCP3170 products.			
Reliability Data Summary:			
Reliability Test Results: NCP3170ADR2G			
Test	Description	Condition	Result
TC	Temperature Cycle	-65C to +150C; 500 cycles	0/240
IOL	Intermittent Operating Life	Delta Tj=100C; 15K cycles	0/240
HAST	Highly Accelerated Temperature and Humidity Stress Test	130C/85% RH Bias; 96 hr	0/160
H3TRB	High Temperature High Humidity Reverse Bias	85C/85% RH Bias; 1008 hr	0/80
RSH	Resistance to Solder Heat	TA=260C; 10 sec	0/90
Electrical Characteristic Summary:			
There is no change in the Electrical Parametric performance.			
List of Affected Standard Parts:			
NCP3170ADR2G			
NCP3170BDR2G			